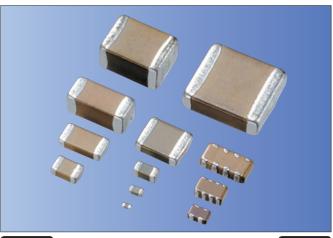
КЧОСЕRа

Kyocera's series of Multilayer Ceramic Chip Capacitors are designed to meet a wide variety of needs. We offer a complete range of products for both general and specialized applications, including general-purpose CM series, high-voltage CF series, low profile CT series, and DM series for automotive uses.

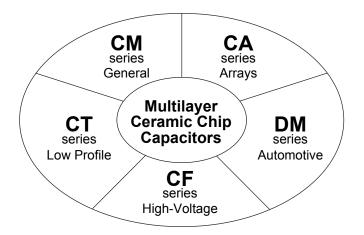
Features

- We have factories worldwide in order to supply our global customer bases quickly and efficiently and to maintain our reputation as one of the highest-volume producers in the industry.
- All our products are highly reliable due to their monolithic structure of high-purity and superfine uniform ceramics and their integral internal electrodes.
- By combining superior manufacturing technology and materials with high dielectric constants, we produce extremely compact components with exceptional specifications.
- Our stringent quality control in every phase of production from material procurement to shipping ensures consistent manufacturing and super quality.
- Kyocera components are available in a wide choice of dimensions, temperature characteristics, rated voltages, and terminations to meet specific configurational requirements.

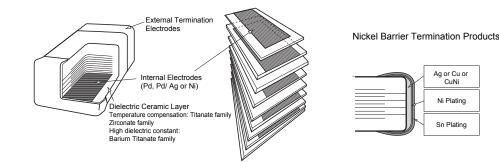


Pb Free





Structure



Tape and Reel



Bulk Cassette



Please contact your local AVX, Kyocera sales office or distributor for specifications not covered in this catalog.

Our products are continually being improved. As a result, the capacitance range of each series is subject to change without notice. Please contact an sales representative to confirm compatibility with your application.



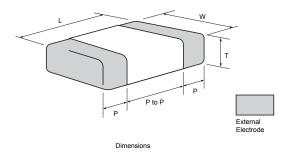
Kyocera Ceramic Chip Capacitors are available for different applications as classified below:

Series	Dieletric Options	Typical Applications	Features	Terminations	Available Size
СМ	C0G (NP0) X5R X7R *X6S *X7S Y5V	General Purpose	Wide Cap Range	Nickel Barrier	0201, 0402, 0603 0805, 1206, 1210 1812
CF	C0G (NP0) X7R	High Voltage & Power Circuits	High Voltage 250VDC, 630VDC 1000VDC, 2000VDC 3000VDC, 4000VDC	Nickel Barrier	0805, 1206, 1210 1812, 2208, 1808 2220
ст	C0G (NP0) X5R X7R Y5V	PLCC (Decoupling)	Low Profile	Nickel Barrier	0402, 0603, 0805 1206, 1210
DM	X7R	Automotive	Thermal shock Resistivity High Reliability	Nickel Barrier	0603, 0805, 1206
CA	C0G (NP0) X5R, X7R	Digital Signal Pass line	Reduction in Placing Costs	Nickel Barrier	0405, 0508

* option



Dimensions



Tape & Reel

Size	EIA CODE	JIS CODE			Dimensio	ons (mm)	<u>-</u>	
Size	EIA CODE	JIS CODE	L	W P min.		P max.	P to P min.	T max.
03	0201	0603	0.6±0.03	0.3±0.03	0.13	0.23	0.20	0.33
05	0402	1005	1.0±0.05	0.5±0.05	0.15	0.35	0.30	0.55
105	0603	1608	1608 1.6±0.10 0.8±0.10 0.20		0.20	0.60	0.50	0.90
21	0805	2012	2.0±0.10	1.25±0.10	0.20	0.75	0.70	1.35
316	1206	3216	3.2±0.20	1.60±0.15	0.30	0.85	1.40	1.75
32	1210	3225	3.2±0.20	2.50±0.20	0.30	1.00	1.40	2.70
42	1808	4520	4.5±0.20	2.00±0.20	0.15	0.85	2.60	2.20
43	1812	4532	4.5±0.30	3.20±0.20	0.30	1.10	2.00	3.00
52	2208	5720	5.7±0.40 2.00±0.20 0.15 0		0.85	4.20	2.20	
55	2220	5750	5.7±0.40	5.00±0.40	0.30	1.40	2.50	2.70

•T (Thickness) depends on capacitance value.

Standard thickness is shown on the appropriate product pages.

CA series (please refer applicable page)

• As for the size of the product specified individually, please contact us.

Bulk Cassette

Size	Size EIA CODE	JIS CODE		w	Ŧ	F	P to P	
5120		JIS CODE	L .	vv	•	min. max.		min.
05	0402	1005	1.0±0.05	0.5±0.05	0.5±0.05	0.15	0.35	0.30
105	0603	1608	1.6±0.07	0.8±0.07	0.8±0.07	0.20	0.60	0.50
21	0805	2012	2.0±0.1	1.25±0.1	1.25±0.1	0.20	0.75	0.70

Note) Regarding support for Bulk cases, please contact us for further information.

Multilayer Ceramic Chip Capacitors Ordering Information



KYOCERA PART NUMBER:		<u>CM 21</u>	<u>X7R</u>	<u>104</u>	<u>< 50</u>	A T	
CM = General Purpose CA CF = High Voltage CT = Low Profile DM = Automotive							
SIZE EIA (JIS) SIZE 03 = 0201 (0603) 21 = 05 = 0402 (1005) 316 = 105 = 0603 (1608) 32 = F12 = 0508 (1220)/ 4cap 42 =	EIA (JIS) SIZE EIA 0805 (2012) 52 22 1206 (3216) 55 22 1210 (3225) D11 04 1808 (4520) D12 05 1812 (4532) 05 05	A (JIS) 08 (5720) 20 (5750) 05 (1012)/ 2cap 08 (1220)/ 2cap					
$\begin{array}{llllllllllllllllllllllllllllllllllll$	X7S (Option)X6S (Option)Y5V						
CAPACITANCE CODE ——							
$\begin{array}{llllllllllllllllllllllllllllllllllll$	cimal point, = 1R5						
TOLERANCE CODE							
$ \begin{array}{ll} A=\pm 0.05 p F \mbox{ (option)} & D=\pm 0.5 p F \\ B=\pm 0.1 p F \mbox{ (option)} & F=\pm 1 p F \\ C=\pm 0.25 p F & G=\pm 2\% \mbox{ (option)} \\ \end{array} $	K = ±10%	Z = -20 to +80%	%				
VOLTAGE CODE							
$\begin{array}{rrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrr$	DC 2000 = 2000VDC DC 3000 = 3000VDC						
A = Nickel Barrier							
PACKAGING CODE B = Bulk C = Bulk Cassette (option) T = 7" Reel Taping & 4mm Cavity pite	H = 7" F	Reel Taping & 4m Reel Taping & 2m Reel Taping & 2m	nm Cavity	pitch			

OPTION –

Thickness max. value is indicated in CT series EX. 125 \rightarrow 1.25mm max. 095 \rightarrow 0.95mm max.

Multilayer Ceramic Chip Capacitors Temperature Characteristics and Tolerance



High Dielectric Constant

EIA Dielectric	Temperature Range	∆C max.
X5R	–55 to 85°C	±1E9/
X7R	–55 to 125°C	±15%
*X7S	–55 to 125°C	1009/
*X6S	–55 to 105°C	±22%
Y5V	–30 to 85°C	-82 to +22%

* option

Temperature Compensation Type

Electric Code Value (pF)	C0G	U∆ N750	SL +350 to -1000
0.5 to 2.7	СК	UK	SL
3.0 to 3.9	CJ	UJ	SL
4.0 to 9.0	СН	UJ	SL
≥10	CG	UJ	SL

 $K=\pm 250ppm/~^\circ C,~J=\pm 120ppm/~^\circ C,~H=\pm 60ppm/~^\circ C,~G=\pm 30ppm/~^\circ C$ e.g. CG = 0±30ppm/ °C

Note: All parts will be marked as "CG" but will conform to the above table.

Available Tolerances

Dielectric materials, capacitance values and tolerances are available in the following combinations only:

EIA Dielectric	Tolerance	Capacitance
	C=±0.25pF	
	D=±0.50pF	*1 <10pF
	F=±1pF	
COG	* ³ A=±0.05pF	<0.5pF
coa	B=±0.1pF	≤5pF
	* ³ G=±2%	> 10 m F
	J=±5%	≥10pF E12 Series
	K=±10%	ETZ Series
X5R X6R	*² K=±10%	E6 Series
X7R	M=±20%	Lo Series
Y5V	Z=-20% to +80%	E3 Series

Note:

*1 Nominal values below 10pF are available in the standard values of 0.5pF, 1.0pF, 1.5pF, 2.0pF, 3.0pF, 4.0pF, 5.0pF, 6.0pF, 7.0pF, 8.0pF, 9.0pF

*2 J = \pm 5% for X7R (X5R) is available on request.

*3 option

E Standard Number

E3	E6	E12	E24 (C	ption)
	1.0	1.0	1.0	1.1
1.0	1.0	1.2	1.2	1.3
1.0	1.5	1.5	1.5	1.6
	1.5	1.8	1.8	2.0
	2.2	2.2	2.2	2.4
2.2	2.2	2.7	2.7	3.0
2.2	3.3	3.3	3.3	3.6
	3.5	3.9	3.9	4.3
	4.7	4.7	4.7	5.1
4.7	4.7	5.6	5.6	6.2
4.7	6.8	6.8	6.8	7.5
	0.0	8.2	8.2	9.1



[RoHS Compliant Products]

This standard type is ideal for use in a wide range of applications,

Features

We offer a diverse product line ranging from ultra–compact (0.6×0.3 mm) to large (4.3×3.2 mm) components configured for a variety of temperature characteristics, rated voltages, and packages. We offer the choice and flexibility for almost any applications.

Temperature Compensation Dielectric

Size (EIA Code)			CM03 (0201)				CM05 (0402)		CM (06	105 03)		CN (08	121 05)	
Temperature Characteristics	c	Δ	U	Δ	SL	CA	UΔ	SL	С	Δ		С	Δ	
Rated Voltage (VDC)	25	50	16	25	25	50	50	50	50	100	16	25	50	100
R20 0.2 R50 0.5 1R0 1.0 1R5 1.5			A											
1R0 1.0 1R5 1.5 2.0 3.0 4.0 5.0 6.0 7.0				_										
8.0 9.0	A	A		A	A									
100 10 120 12 15 18 22 27 39 47 56 68 68 62 101 100							в	в		с —				
27 33 39 47						В								
56 68 82 101 100 121 120														
150 180 220														D
270 330									c				D	
470 560 680 820 102 1000 122 1200														
122 1200 1500 1800 2200 2700													E	
3300												E G		
3900 4700 5600 6800 8200											G			
8200 103 10000 123 12000 15000 18000														

Applications

from commercial to industrial equipment.

Thickness and standard package quantity

Size	*03	*05	105	*105				2	21, 316, 32	2			
Thickness	Α	В	С	С	D	Е	F	G	Н	I	J	К	L
(mm)	0.3±0.03	0.5±0.05	0.8±0.1	0.8±0.1	0.6±0.1	0.85±0.1	1.15±0.1	1.25±0.1	1.4 max.	1.6 max.	1.6±0.15	2.0±0.2	2.5±0.2
Taping (180 dia reel)	15kp (P8)	10kp (P8)	4kp (P8)	8kp (P8)	4kp (P8)	4kp (P8)	3kp (E8)	3kp (E8)	3kp (E8)	2.5kp (E8)	2.5kp (E8)	2kp (E8)	1kp (E8)
Taping (330 dia reel)	50kp (P8)	50kp (P8)	10kp (P8)	20kp (P8)	10kp (P8)	10kp (P8)	10kp (E8)	10kp (E8)	10kp (E8)	5kp (E8)	5kp (E8)	5kp (E8)	—

Size		4	3	
Thickness	J	К	L	М
(mm)	1.6±0.15	2.0±0.2	2.5±0.2	2.8±0.2
Taping (180 dia reel)	1kp (E12)	1kp (E12)	0.5kp (E12)	0.5kp (E12)
Taping (330 dia reel)	—	—	—	_

Note: P8 = 8mm width paper tape E8 = 8mm width plastic tape

E12 = 12mm width plastic tape

* Carrier tape 2mm pitch from one capacitor to another.

CM Series Nickel Barrier Terminations



[RoHS Compliant Products]

X5R Dielectric

	Size Code)			CM03 (0201					CN (04	105 02)					CM (06	105 03)				CM21 (0805)				
	/oltage (VDC) itance (pF)	4	6.3	10	16	25	4	6.3	10	16	25	50	4	6.3	10	16	25	50	4	6.3	10	16	25	50
101	100																							
151	150 220 330					А																		
102	470 680 1000											в												
152	1500 2200 3300				A																			
103	4700 6800 10000			Α							в							с						
153	15000 22000 33000																							D E
104	47000 68000 100000									В							с	с с						G
154	150000 220000 330000							В															G	
105	470000 680000 1000000														с	с						G		
155	1500000 2200000 3300000																				G	G		
106	4700000 6800000 10000000																		<i></i>	G	G			
156	1500000 22000000												*////									*////		
476	33000000 47000000																							

	Size A Code)			CM316 (1206)						132 10)			CN (18	l43 12)
	Voltage (VDC) citance (pF)	6.3	10	16	25	50	4	6.3	10	16	25	50	6.3	50
104	100000													
	220000 470000				F	F						н		
105	1000000										н	ĸ		
	2200000				J						К			L
106	4700000 10000000	J	J	J					К					
107	22000000 47000000 10000000								L				М	

Optional Spec.

Thickness and standard package quantity

Size	*03	*05	105	*105				2	21, 316, 32	2			
Thickness	Α	В	С	С	D	Е	F	G	Н	1	J	К	L
(mm)	0.3 <u>+</u> 0.03	0.5 ± 0.05	0.8 <u>+</u> 0.1	0.8 <u>+</u> 0.1	0.6 <u>+</u> 0.1	0.85±0.1	1.15 <u>+</u> 0.1	1.25 <u>+</u> 0.1	1.4 max.	1.6 max.	1.6±0.15	2.0 <u>+</u> 0.2	2.5 <u>+</u> 0.2
Taping (180 dia reel)	15kp (P8)	10kp (P8)	4kp (P8)	8kp (P8)	4kp (P8)	4kp (P8)	3kp (E8)	3kp (E8)	3kp (E8)	2.5kp (E8)	2.5kp (E8)	2kp (E8)	1kp (E8)
Taping (330 dia reel)	50kp (P8)	50kp (P8)	10kp (P8)	20kp (P8)	10kp (P8)	10kp (P8)	10kp (E8)	10kp (E8)	10kp (E8)	5kp (E8)	5kp (E8)	5kp (E8)	—

Size		4	3	
Thickness	J	Κ	L	М
(mm)	1.6±0.15	2.0±0.2	2.5 <u>+</u> 0.2	2.8±0.2
Taping (180 dia reel)	1kp (E12)	1kp (E12)	0.5kp (E12)	0.5kp (E12)
Taping (330 dia reel)	—	_	—	—

Note: P8 = 8mm width paper tape E8 = 8mm width plastic tape E12 = 12mm width plastic tape

 \ast Carrier tape 2mm pitch from one capacitor to another.



[RoHS Compliant Products]

X7R, Dielectric

S (EIA	ize Code)		CM03 (0201)			CM05 (0402)			<u> </u>		105 03)				·	CN (08	121 05)		
	oltage (VDC) tance (pF)	10	16	25	16	25	50	6.3	10	16	25	50	100	6.3	10	16	25	50	100
101	100																		
151	150 220 330		А	A															
102	470 680 1000						в						с						
152	1500 2200 3300	A																	
<u>103</u> 153	4700 6800 10000	A			в –	В						с							D E
153	15000 22000 33000										с							DE	G
104	47000 68000 100000									с	С	C C						G	
154	150000 220000 330000								С							G	G		
105	470000 680000 1000000														G				
155	1500000 2200000 3300000																		
106	4700000 10000000																		

	Size Code)				316 06)					CM32 (1210)			CN (18	143 12)
	oltage (VDC) itance (pF)	6.3	10	16	25	50	100	10	16	25	50	100	50	100
103	10000													
104	22000 47000 100000					Е	F					Н		
105	220000 470000 1000000			F	F	F	J			н	<u>н</u> к	K L	К	L
106	2200000 4700000 10000000 22000000		J					L	L	К			L	

Optional Spec.

Y5V Dielectric

	Size Code)		103 01)			105 02)				105 03)			CN (08	121 05)			CM316 (1206)			CM32 (1210)	
	oltage (VDC) itance (pF)	6.3	10	10	16	25	50	10	16	25	50	10	16	25	50	10	16	25	10	16	25
102 472	1000 2200 4700		А				в														
103 473	10000 22000 47000	А			в	в	В				с										
104 474	100000 220000 470000			В					с	С			E	D E	E G						
105 475	1000000 2200000 4700000							С				G	G	G			F	F			
106 476	1000000 2200000 4700000															J	J		К		

Thickness and standard package quantity

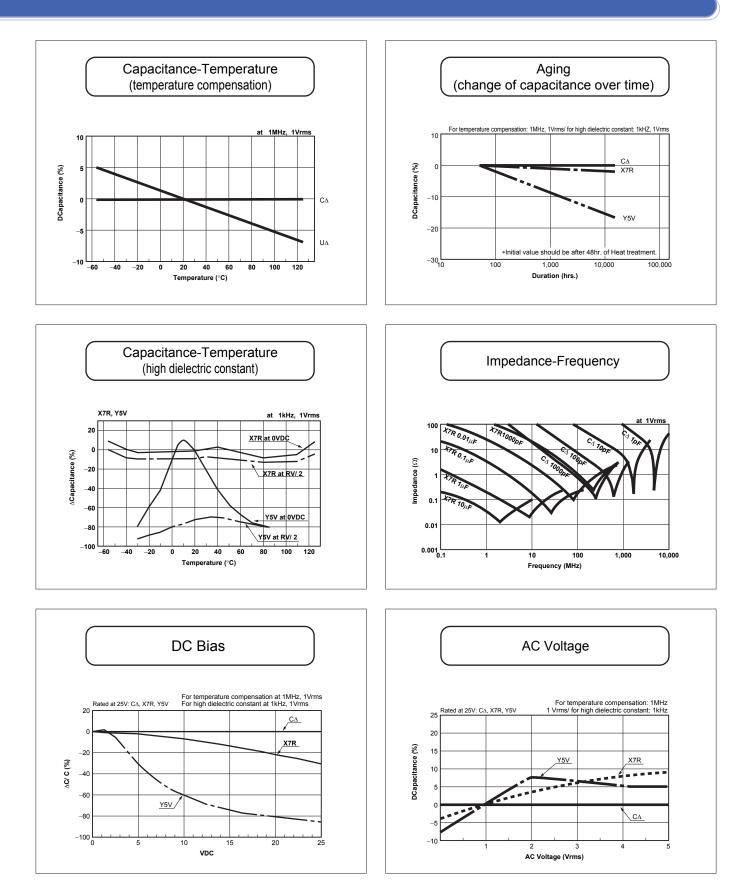
Size	*03	*05	105	*105				2	21, 316, 32	2			
Thickness	Α	В	С	С	D	Е	F	G	Н	1	J	Κ	L
(mm)	0.3±0.03	0.5±0.05	0.8±0.1	0.8±0.1	0.6±0.1	0.85±0.1	1.15±0.1	1.25±0.1	1.4 max.	1.6 max.	1.6±0.15	2.0±0.2	2.5±0.2
Taping (180 dia reel)	15kp (P8)	10kp (P8)	4kp (P8)	8kp (P8)	4kp (P8)	4kp (P8)	3kp (E8)	3kp (E8)	3kp (E8)	2.5kp (E8)	2.5kp (E8)	2kp (E8)	1kp (E8)
Taping (330 dia reel)	50kp (P8)	50kp (P8)	10kp (P8)	20kp (P8)	10kp (P8)	10kp (P8)	10kp (E8)	10kp (E8)	10kp (E8)	5kp (E8)	5kp (E8)	5kp (E8)	—

Size		4	3	
Thickness	J	Κ	L	М
(mm)	1.6±0.15	2.0±0.2	2.5±0.2	2.8±0.2
Taping (180 dia reel)	1kp (E12)	1kp (E12)	0.5kp (E12)	0.5kp (E12)
Taping (330 dia reel)	—	—	_	_

Note: P8 = 8mm width paper tape E8 = 8mm width plastic tape E12 = 12mm width plastic tape

 \ast Carrier tape 2mm pitch from one capacitor to another.

Multilayer Ceramic Chip Capacitors Electrical Characteristics



🔇 КУОСЕRа

Please verify individual characteristics at the design stage to ensure total suitability.



Test Conditions and Specifications for Temperature Compensation type (CA to UA • SL Characteristics)

Test	Items	Specifications (C: nominal capacitance)			Tes	t Conditions	
Capacitance V	/alue	Within tolerance	Г	C≤1000	ΩnF	1MHz±10%	0.5.1
Q		C≥30pF: Q≥1000 C<30pF: Q≥400+20C		C>1000		1kHz±10%	0.5 to 5Vrms
Insulation res	istance (IR) (*5)	10,000M\Omega or 500M\Omega ${\boldsymbol{\cdot}}\mu F$ min., whichever is less				ated voltage is ap m temperature a	
Dielectric resi	stance (*5)	No problem observed	(*	1) Apply 3 tir	mes of th	ne rated voltage fo	r 1 to 5 seconds
Appearance		No problem observed	Ν	licroscope	e (10×	magnification)	
Termination s	trength	No problem observed		pply a side ounted sam		rce of 500g (5N) ^(*2) to a PCB-
Bending stren	ngth	No mechanical damage at 1mm bent		lass epoxy pacing: 90m		1.6mm); fulcrum 0 seconds.	
Vibration	Appearance	No significant change is detected				cy: 10 to 55 (I	Hz)
test	ΔC	Within tolerance	S		conditi	on: 10→55→ ⁻	10Hz/ min.
	Q	C≥30pF: Q≥1000 C<30pF: Q≥400+20C		n X, Y and hours ea		ections: al 6 hours	
Soldering heat	Appearance	No significant change is detected		oak the s older for 1		in 260°C±5°C	;
resistance	ΔC	$\pm 2.5\%$ or $\pm 0.25 pF$ max., whichever is larger	a	nd place i	in a ro	om at normal	
	Q	C≥30pF: Q≥1000 C<30pF: Q≥400+20C		Preheatin	ng Con		
	IR (*5)	10,000M\Omega or 500MΩ ${\scriptstyle \bullet }\mu F$ min., whichever is smaller		Order 1		to 100°C	2 minutes
	Withstand voltage(*5)	Resists without problem		2		0 to 200°C	2 minutes
Solderability		Ni/ Br termination: 90% min.	S	oaking Co Sn63 So Sn-3Ag-(lder	n 235±5°C 245±5°C	2±0.5 sec. 3±0.5 sec.
Temperature	Appearance	No significant change is detected	((Cycle)			
cycle	ΔC	$\pm 2.5\%$ or $\pm 0.25 pF$ max., whichever is larger	Ň	ormal roo		perature (3 m	,
	Q	C≥30pF: Q≥1000 C<30pF: Q≥400+20C	N	ormal roc	om ten	temperature perature (3 m temperature	iin.) →
	IR (*5)	10,000M Ω or 500M $\Omega {\ensuremath{\cdot}} \mu F$ min., whichever is smaller		0 1			
	Withstand voltage(*5)	Resists without problem	A	fter five c	ycles,	measure after	24±2 hours.
Load	Appearance	No significant change is detected	_	ftor applir	oa rata	d voltage for	
humidity test (*4)	ΔC	$\pm7.5\%$ or $\pm0.75pF$ max., whichever is larger	5	00+24/ -0) hours	d voltage for in pre-condi	
	Q	C≥30pF: Q≥200 C<30pF: Q≥100+10C/ 3	tc	o stabilize	for 48	90 to 95%RH ±4 hours, at ro re making me	oom
	IR (*5)	500M\Omega or 25M\Omega ${}^{\bullet}\mu F$ min., whichever is smaller		Inperatur	e beit	ie making me	asurements.
High-	Appearance	No significant change is detected					
temperature with	ΔC	$\pm 3\%$ or $\pm 0.3 pF$ max., whichever is larger					
loading	Q	$\pm 3\%$ or ± 0.3 pF max., whichever is largerAfter applying (*1) twice of the rated w at a temperature of $125\pm3^{\circ}$ C for 10 pF \leq C \leq 30 pF: Q \geq 275 \pm 5C/2 C \leq 10 pF: Q \geq 200 \pm 10CAfter applying (*1) twice of the rated w at a temperature of $125\pm3^{\circ}$ C for $1000\pm48/-0$ hours, measure the sar after storing 24 ± 2 hours.					
	IR (*5)	1,000M Ω or 50M $\Omega \cdot \mu F$ min., whichever is smaller					

*1 For the CF series, use 1.5 times when the rated voltage is 250V; use/ 1.2 times when the rated voltage exceeds 630V.

*4 Except CF series.

*5 The charge and discharge current of the capacitor must not exceed 50mA.

*2 2N at 0201 Size

*3 Apply 500V for 1 minute in case the rated voltage is 630V or higher.



Test Conditions and Specifications for High Dielectric Type (X5R, X7R, Y5V)

Test	Items	Specific		-	Test Conditions				
		X7R/ X5R	Y5V	Do previou	s treatment (*8, *14)				
Capacitance \ tanδ (%)	/alue	Within tolerance 2.5% max., 3.5% max. (*2), 7.0% max. (*12) 5.0% max. (*3), 7.5% max. (*17)	5.0% max., 7.0% max. (*13) 9.0% max. (*4), 12.5% max. (*5)	- Capacita C≤10μ C>10μ	nce Fire Fire 1kHz±10% 1	Vol .0±0.2Vrms			
Insulation res	istance (IR) (*15)	10,000MΩ or 500MΩ • μF min.,		Measured after	er the rated voltage is app n temperature and humid	lied for 2 minutes			
Dielectric resi	stance (*15)	No problem observed			imes of the rated voltage for	•			
Appearance		No problem observed		Microscope	e (10×magnification))			
Termination s	trength (*6)	No problem observed		Apply a sidew PCB-mounte	vard force of 500g (5N)	^{•16)} to a			
Bending strer	ngth test (*6)	No problem observed at 1mm b	ent	Glass epoxy P	CB (*03, 05 type and CA g: 90mm; for 10 seconds.	Series: T=0.8mm);			
Vibration	Appearance	No significant change is detecte	d	Vibration fr	equency: 10 to 55 (Hz)			
test		Within tolerance		Amplitude: 1.5mm Sweeping condition: 10→55→10Hz/ min					
	tanδ (%)	Satisfies the initial value			Z directions:				
Soldering	Appearance	No significant change is detecte	d	2 hours each Total 6 hours Do previous treatment (*8)					
heat resistance	Δ C	Within ±7.5%	Within ±20%	solder for 1	ample in 260°C±5°0 0±0.5 seconds n a room at normal				
	tan δ (%)	Satisfies the initial value		and humidi	ity; measure after 48 g Conditions)				
	IR (*15)	10,000MΩ or 500MΩ • μF min.,	whichever is smaller	Order	Temperature	Time			
	Withstand voltage (*15)	Resists without problem		1 2	80 to 100°C 150 to 200°C	2 minutes 2 minutes			
Solderability		Ni/ Br termination: 90% min.		Soaking Co Sn63 Sol Sn-3Ag-0	der 235±5°C	2±0.5 sec. 3±0.5 sec.			
Temperature	Appearance	No significant change is detecte	d	Do previous treatment (*8)					
cycle	ΔC	Within ±7.5%	Within ±20%	 (Cycle) Normal roc 	om temperature (3 n	nin.) →			
	tanδ (%)	Satisfies the initial value			eration temperature om temperature (3 n				
	IR (*15)	10,000MΩ or 500MΩ • μF min.,	whichever is smaller		eration temperature	,			
	Withstand voltage (*15)	Resists without problem		After five c	ycles, measure afte	r 48 <u>+</u> 4hours.			
Load	Appearance	No significant change is detecte	d		s treatment (*9)				
humidity test (*11)	ΔC	Within ±12.5%	Within ±30%		ing rated voltage at d humidty 90 to 95%	6RH,			
	tanδ (%)	200% max. of initial value	150% max. of initial value		/ –0 hours and keep or 48±4 hours then r				
	IR (*15)	500MΩ or 25MΩ • μ F min., whic	hever is smaller		the specification lim				
High-	Appearance	No significant change is detecte	d	Do previou	s treatment (*9)				
temperature with	ΔC	Within ±12.5%	Within ±30%	After apply	ing twice (*7) of the r				
loading	tanδ (%)	200% max. of initial value	150% max. of initial value		he highest operating 8/ –0 hours, measu				
	IR (*15)	1,000MΩ or 50MΩ • μF min., wh	ichever is smaller	after storin	g 48±4 hours.				
		l							

*1 Use 1.5 times when the rated voltage is 250V or over.

Use 1.2 times when the rated voltage is 630V or over.

*2 X7R 16V/ 25V type.

*3 Apply to X5R16V/ 25V type, X7R 6.3V/ 10V type.

*4 Apply to Y5V 16V type, CM32Y5V335 to 106 (25V Type).

*5 Apply to Y5V 6.3V/ 10V type. Apply 16% max. to CM21Y5V106/ CM316Y5V226.

*6 Exclude CT series with thickness of less than 0.66mm and CA series.

*7 Use 1.5 times when the rated voltage is 4V/ 6.3V/ 10V/ 250V and 100V (32X7R474/ 43X7R105/ 55X7R105).

Use 1.2 times when the rated voltage is 630V or over. *8 Keep specimen at $150^{\circ}C+0/-10^{\circ}C$ for one hour, leave specimen at room ambient

*8 Keep specifien at $150^{\circ}C+0/=10^{\circ}C$ for one nour, leave specifien at room ambien for 48 ± 4 hours.

*9 Apply the same test condition for one hour, then leave the specimen at room ambient for 48±4 hours. *10 $\,$ For the CF series over 630V, apply 500V for 1 minute at room ambient.

*11 Except CF series.

*12 Apply to X5R 10V type.

*13 Apply to 25V series of CM105Y5V154 over, CM21Y5V105 over, 316Y5V155 over.

*14 Measurement condition 1kHz, 1Vrms for Y5V, C<47 μF type.

*15 The charge/ discharge current of the capacitor must not exceed 50mA.

*16 2N at 0201 Size

*17 Apply to X5R 4V and 6.3V type.

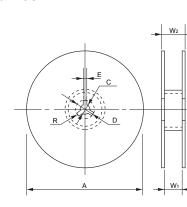
* The above test conditions and standards do not apply to products with optional specifications.

Multilayer Ceramic Chip Capacitors Packaging Options

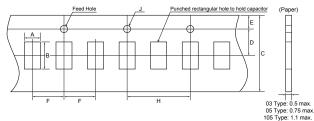
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Tape and Reel

• Reel



F=2mm (03, 05, 105 Type)



(Plastic)

<u>2.8 max.</u>

φ1.0^{+0.}

0.6

φ1.0 ^{+0.4}

0.6 max

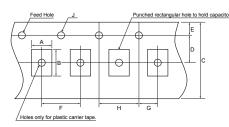
(Plastic)

2.8 max

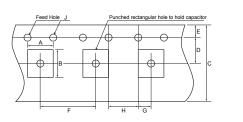
(Paper)

→|-+ 1.1 max

F=4mm (105, D11, D12, F12, 21, 316, 32, 42, 52 Type)

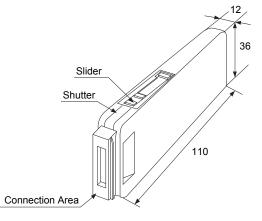


F=8mm (43, 55 Type)





(Unit: mm)



Reel

Reel				(Unit: mm)
Code Reel	А	В	С	D
7-inch Reel (CODE: T, H)	$180^{+0}_{-2.0}$	φ60 min.	13+0.5	21+0.8
13-inch Reel (CODE: L, N)	330 <u>+</u> 2.0	¢100±1.0	13±0.5	21±0.8
Code Reel	E	W 1	W2	R
7-inch Reel (CODE: T, H)	2.0+0.5	10.0±1.5	16.5 max.	1.0
13-inch Reel (CODE: L, N)	2.0 <u>±</u> 0.5	9.5±1.0	TO.5 Max.	1.0

* Carrier tape width 8mm.

For size 42 (1808) or over, Tape width 12mm and W1: 14 \pm 1.5, W2: 18.4mm max.

Carrier Tape			(Unit: mm)
Туре	А	в	F
03 (0.6×0.3)	0.37 <u>+</u> 0.03	0.67±0.03	2.0 <u>+</u> 0.05
05 (1.0×0.5)	0.65±0.1	1.15 <u>+</u> 0.1	2.0±0.05
105 (1.6×0.8)	1.0 <u>+</u> 0.2	1.8 <u>+</u> 0.2	4.0 <u>+</u> 0.1
D11 (1.37×1.0)	1.15±0.2	1.55±0.2	4.0±0.1
D12 (1.25×2.0)	1.5±0.2	2.3±0.2	4.0±0.1
F12 (1.25×2.0)	1.5±0.2	2.3±0.2	4.0±0.1
21 (2.0×1.25)	1.5 <u>+</u> 0.2	2.3 <u>+</u> 0.2	4.0 <u>+</u> 0.1
316 (3.2×1.6)	2.0 <u>+</u> 0.2	3.6±0.2	4.0 <u>+</u> 0.1
32 (3.2×2.5)	2.9±0.2	3.6±0.2	4.0±0.1
42 (4.5×2.0)	2.4±0.2	4.9±0.2	4.0±0.1
43 (4.5×3.2)	3.6±0.2	4.9±0.2	8.0±0.1
52 (5.7×2.0)	2.4 <u>±</u> 0.2	6.0±0.2	4.0±0.1
55 (5.7×5.0)	5.3±0.2	6.0±0.2	8.0 <u>+</u> 0.1

						(Jnit: mm)
F	Carrier Tape	С	D	Е	G	н	J
2.0 ±0.05	8mm Paper	8.0 ±0.3	3.5 ±0.05	1.75 ±0.1	2.0 ±0.05	4.0 ±0.1	1.5 +0.1/ –0
4.0 ±0.1	8mm Plastic						
8.0 ±0.1	12mm Plastic	12.0 ±0.3	5.5 ±0.05				



Circuit Design

- 1. Once application and assembly environments have been checked, the capacitor may be used in conformance with the rating and performance which are provided in both the catalog and the specifications. Use exceeding that which is specified may result in inferior performance or cause a short, open, smoking, or flaming to occur, etc.
- 2. Please consult the manufacturer in advance when the capacitor is used in devices such as: devices which deal with human life, i.e. medical devices; devices which are highly public orientated; and devices which demand a high standard of liability. Accident or malfunction of devices such as medical devices, space equipment and devices having to do with atomic power could generate grave consequence with respect to human lives or, possibly, a portion of the public. Capacitors used in these devices may require high reliability design different from that of general purpose capacitors.
- 3. Please use the capacitors in conformance with the operating temperature provided in both the catalog and the specifications. Be especially cautious not to exceed the maximum temperature. In the situation the maximum temperature set forth in both the catalog and specifications is exceeded, the capacitor's insulation resistance may deteriorate, power may suddenly surge and short-circuit may occur. The capacitor has a loss, and may self-heat due to equivalent series resistance when alternating electric current is passed therethrough. As this effect becomes especially pronounced in high frequency circuits, please exercise caution. When using the capacitor in a (self-heating) circuit, please make sure the surface of the capacitor remains under the maximum temperature for usage. Also, please make certain temperature rises remain below 20°C.
- 4. Please keep voltage under the rated voltage which is applied to the capacitor. Also, please make certain the peak voltage remains below the rated voltage when AC voltage is super-imposed to the DC voltage.
 In the situation where AC or pulse voltage is employed, ensure average peak voltage does not exceed the rated voltage.
 Exceeding the rated voltage provided in both catalog and specifications may lead to defective withstanding voltage or, in worst case situations, may cause the capacitor to smoke or flame.
- 5. When the capacitor is to be employed in a circuit in which there is continuous application of a high frequency voltage or a steep pulse voltage, even though it is within the rated voltage, please inquire to the manufacturer. In the situation the capacitor is to be employed using a high frequency AC voltage or a extremely fast rising pulse voltage, even though it is within the rated voltage, it is possible capacitor reliability will deteriorate.
- 6. It is a common phenomenon of high-dielectric products to have a deteriorated amount of static electricity due to the application of DC voltage. Due caution is necessary as the degree of deterioration varies depending on the quality of capacitor materials, capacity, as well as the load voltage at the time of operation.
- 7. Do not use the capacitor in an environment where it might easily exceed the respective provisions concerning shock and vibration specified in the catalog and specifications.

In addition, it is a common piezo phenomenon of high dielectric products to have some voltage due to vibration or to have noise due to voltage change. Please contact sales in such case.

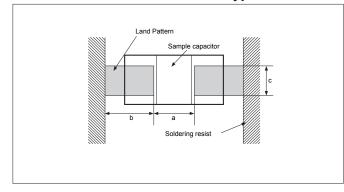
- 8. If the electrostatic capacity value of the delivered capacitor is within the specified tolerance, please consider this when designing the respective product in order that the assembled product function appropriately.
- 9. Please contact us upon using conductive adhesives.

Storage

- 1. If the component is stored in minimal packaging (a heat-sealed or chuck-type plastic bag), the bag should be kept closed. Once the bag has been opened, reseal it or store it in a desiccator.
- 2. Keep storage place temperature +5 to +35 degree C, humidity 45 to 70% RH.
- 3. The storage atmosphere must be free of gas containing sulfur and chlorine. Also, avoid exposing the product to saline moisture. If the product is exposed to such atmospheres, the terminals will oxidize and solderability will be effected.
- 4. Precautions 1) to 3) apply to chip capacitors packaged in carrier tapes and bulk cases.
- 5. The solderability is assured for 12 months from our shipping date (six months for silver palladium) if the above storage precautions are followed.
- 6. Chip capacitors may crack if exposed to hydrogen (H₂) gas while sealed or if coated with silicon, which generates hydrogen gas.

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Dimensions for recommended typical land



When mounting the capacitor to the substrate, it is important to consider carefully that the amount of solder (size of fillet) used has a direct effect upon the capacitor once it is mounted.

- a) The greater the amount of solder, the greater the stress to the elements. As this may cause the substrate to break or crack, it is important to establish the appropriate dimensions with regard to the amount of solder when designing the land of the substrate.
- b) In the situation where two or more devices are mounted onto a common land, separate the device into exclusive pads by using soldering resist.

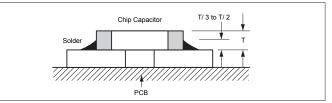
L×W	а		
	a	b	С
0.6×0.3	0.20 to 0.30	0.25 to 0.35	0.30 to 0.40
1.0×0.5	0.30 to 0.50	0.35 to 0.45	0.40 to 0.60
1.6×0.8	0.70 to 1.00	0.80 to 1.00	0.60 to 0.80
2.0×1.25	1.00 to 1.30	1.00 to 1.20	0.80 to 1.10
3.2×1.6	2.10 to 2.50	1.10 to 1.30	1.00 to 1.30
3.2×2.5	2.10 to 2.50	1.10 to 1.30	1.90 to 2.30
4.5×2.0	2.50 to 3.20	1.80 to 2.30	1.50 to 1.80
4.5×3.2	2.50 to 3.20	1.80 to 2.30	2.60 to 3.00
5.7×2.0	4.20 to 4.70	2.00 to 2.50	1.50 to 1.80
5.7×5.0	4.20 to 4.70	2.00 to 2.50	4.20 to 4.70
	1.0×0.5 1.6×0.8 2.0×1.25 3.2×1.6 3.2×2.5 4.5×2.0 4.5×3.2 5.7×2.0	1.0×0.5 0.30 to 0.50 1.6×0.8 0.70 to 1.00 2.0×1.25 1.00 to 1.30 3.2×1.6 2.10 to 2.50 3.2×2.5 2.10 to 2.50 4.5×2.0 2.50 to 3.20 4.5×3.2 2.50 to 3.20 5.7×2.0 4.20 to 4.70 5.7×5.0 4.20 to 4.70	1.0×0.5 0.30 to 0.50 0.35 to 0.45 1.6×0.8 0.70 to 1.00 0.80 to 1.00 2.0×1.25 1.00 to 1.30 1.00 to 1.20 3.2×1.6 2.10 to 2.50 1.10 to 1.30 3.2×2.5 2.10 to 2.50 1.10 to 1.30 4.5×2.0 2.50 to 3.20 1.80 to 2.30 4.5×3.2 2.50 to 3.20 1.80 to 2.30 5.7×2.0 4.20 to 4.70 2.00 to 2.50

* CA series: Please refer applicable page.

Automotive Series

Automotive Series (Unit: mm)				
Size	L×W	а	b	С
105	1.6×0.8	0.60 to 0.90	0.80 to 1.00	0.70 to 1.00
21	2.0×1.25	0.90 to 1.20	0.80 to 1.20	0.90 to 1.40
316	3.2×1.6	1.40 to 1.90	1.00 to 1.30	1.30 to 1.80

Ideal Solder Thickness



Typical mounting problems

Item	Not recommended example	Recommended example/ Separated by solder		
Multiple parts mount		Solder resist		
Mount with leaded parts	Leaded parts	Solder resist Leaded parts		
Wire soldering after mounting	Soldering iron Wire	Solder resist		
Overview		Solder resist		



Mounting Design

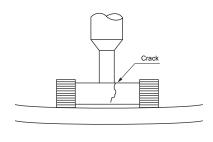
The chip could crack if the PCB warps during processing after the chip has been soldered.

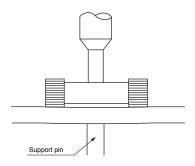
Recommended chip position on PCB to minimize stress from PCB warpage



Actual Mounting

- 1) If the position of the vacuum nozzle is too low, a large force may be applied to the chip capacitor during mounting, resulting in cracking.
- 2) During mounting, set the nozzle pressure to a static load of 100 to 300 gf.
- 3) To minimize the shock of the vaccum nozzle, provide a support pin on the back of the PCB to minimize PCB flexture.





- 4) Bottom position of pick up nozzle should be adjusted to the top surface of a substrate which camber is corrected.
- 5) To reduce the possibility of chipping and cracks, minimize vibration to chips stored in a bulk case.
- 6) The discharge pressure must be adjusted to the part size. Verify the pressure during setup to avoid fracturing or cracking the chips capacitors.

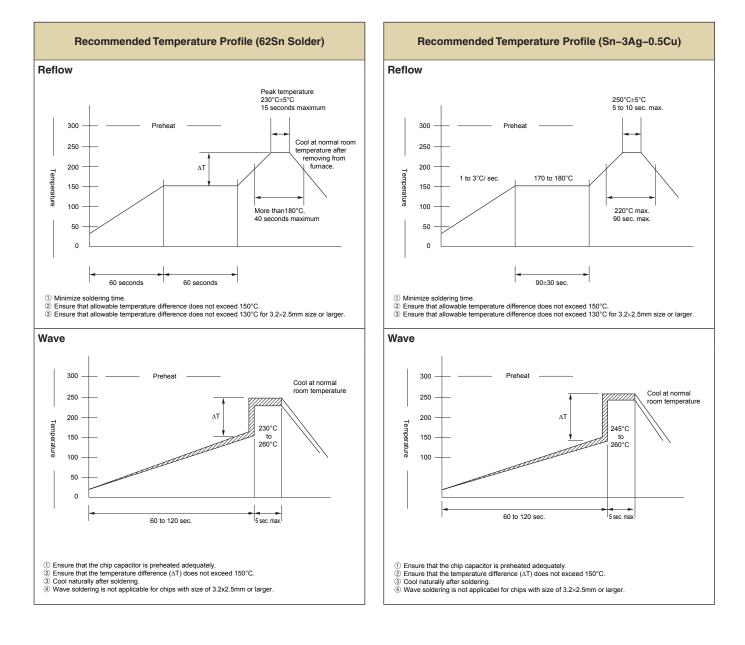
Resin Mold

- 1) If a large amount of resin is used for molding the chip, cracks may occur due to contraction stress during curing. To avoid such cracks, use a low shrinkage resin.
- 2) The insulation resistance of the chip will degrade due to moisture absorption. Use a low moisture absorption resin.
- 3) Check carefully that the resin does not generate a decomposition gas or reaction gas during the curing process or during normal storage. Such gases may crack the chip capacitor or damage the device itself.



Soldering Method

- 1) Ceramic is easily damaged by rapid heating or cooling. If some heat shock is unavoidable, preheat enough to limit the temperature difference (Delta T) to within 130 degree Celsius.
- 2) The product size 1.0×0.5mm to 3.2×1.6mm can be used in reflow and wave soldering, and the product size of over 3.2×2.5mm, 0.6×0.3mm, and capacitor arrays can be used in reflow.
- Circuit shortage and smoking can be created by using capacitors which are used neglecting the above caution.
- 3) Please see our recommended soldering conditions.
- 4) In case of using Sn-Zn Solder, please contact us in advance.



Sodering iron

- 1) Temperature of iron chip
- 2) Wattage
- 3) Tip shape of soldering iron
- 4) Soldering Time

380°C max. 80W max. φ3.0mm max. 3 sec. max.

5) Cautions

- a) Pre–heating is necessary Rapid heating must be avoided. Delta T ${\leq}150^{\circ}C$
- b) Avoid direct touching to capacitors.
- c) Avoid rapid cooling after soldering. Natural cooling is recommended.